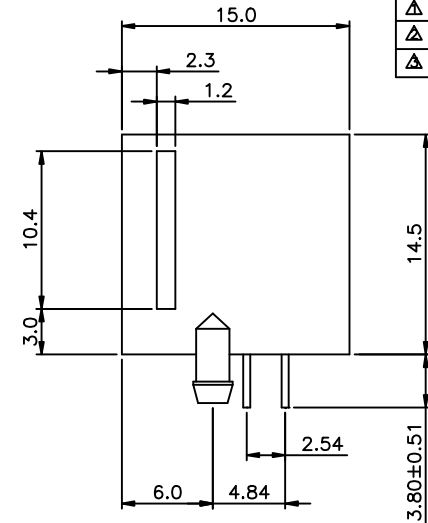
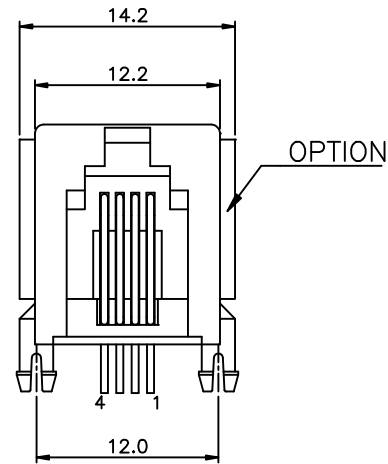




REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
Δ		ADD PART NUMBER	OSJ 7/22/05*	
Δ		PART NUMBER MODIFY	OSJ 8/3/05*	
Δ		ADD P/N.	CT 8/06/05*	

NOTES:

ELECTRICAL:

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 30 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

1. HOUSING MATERIAL : PBT+30%.G.F.&PBT+15%G.F UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE Ø0.46mm.
3. PLATING : GOLD PLATING OVER NICKEL.
4. OPERATING LIFE : 750 CYCLES MIN.
5. PCB RETENTION PRE-SOLDER : 1 LB MIN.
6. PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

1. STORAGE : -40°C TO +85°C.
2. OPERATION: 0°C TO 70°C.
3. WAVE SOLDERING TEMPERATURE: 230~250°C (3~5 SECONDS)

MATES WITH MODULAR PLUG CONFORMING TO

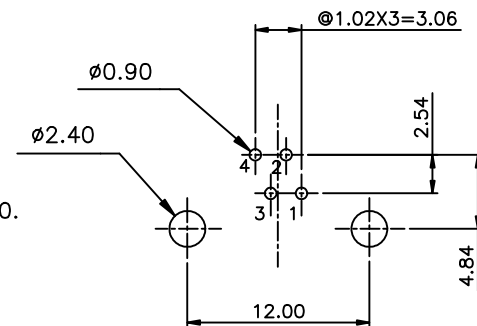
FCC PART 68, SUBPART F.

FREE LEAD PART NUMBER: E554X-HOLXXX-L

2-2C
4-4C

1- 3u" 2- 6u"
3-15u" 4-30u"
5-50u" 6-Pd 20u"

1Q:A06-2270-L W/ OPTION
1R:A06-2380-L w/ OPTION Δ Δ
01:A06-1010-L w/ OPTION Δ



PC Board Layout

DETACHED LISTS	MM (INCH)	DFTO YAN	DATE 04/12/05*	FULL RISE ELECTRONIC CO., LTD	
	TOLERANCES EXCEPT AS NOTED	CHKD	DATE		
	MM	MFO	DATE		
	.0 ±0.2 .00 ±0.15 .000 ±0.075	APPVL XLF	DATE 08/09/05*		
ANGLES ± 0.5		MATERIAL :		TITLE SIDE ENTRY L/P PCB JACK	
THIRD ANGLE PROJECTION		QT'Y :			
		FINISH :		DRAWING NO. GE553A08-LC	
		SCALE : 1:1		/PART NO. SEENOTE	
		DO NOT SCALE DRAWING		SIZE A3	REV 3
		SHEET X		OF Y	